IMPREGNANTS IMPREGNANTY

4. IMPREGNATING RESIN VUPOXY/ Epoxy resin/ PLASTISOL lead free





IMPREGNANTS (WWW.) WIRES









Aplication:

Plastisol lead free is modificated and pigmented one component epoxy resin used for impregnating of windings. Plastisol is resin with low VOC. It makes homogenous film which isolate non isolated profile wires used for winding.

Description:

Trickling resin VUPOXY E - 1K is one — component impregnating resin based on modified epoxy resin. It is typical for its low level of volatile substance — "VOC = 0", an excellent mechanical strength, very good penetration into the winding, short curing time at 160 °C By 1K E-2007 impregnated windings have an excellent mechanical strength, and a considered resistance to vapor solvents, transformer oils and refrigerator liquids.

Processing data and properties of liquid resin:

Density (DIN 53 217)	25°C	[g/cm³]	1,25 ± 0,04
Viscosity Brookfield, 254°C	25 ° C	[mPa.s]	4500 - 5500
Shelf- life	5 - 25 ° C	[months]	min. 6
Colour			black
Film properties			
Thickness		[mm]	0,5 -0,8
Solids % by weight		100 % 1 hr at 165 °C	
Adherence to steel and copper (after burning at 160°C 0,5 hrs		satisfied	
Surface after burning		Coherent coating without bubles	



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